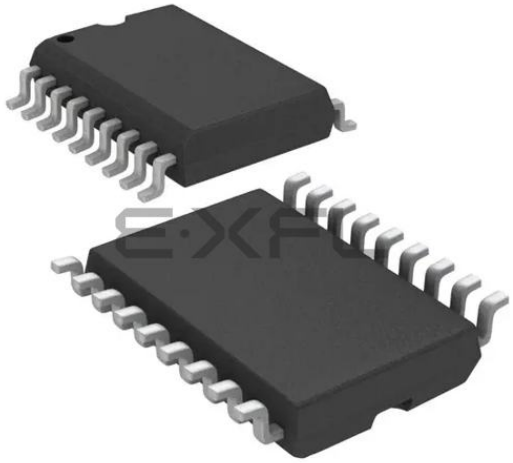

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	32MHz
Connectivity	I²C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	15
Program Memory Size	14KB (8K x 14)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 12x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	18-SOIC (0.295", 7.50mm Width)
Supplier Device Package	18-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lf1847-i-so

REGISTER 5-2: OSCSTAT: OSCILLATOR STATUS REGISTER

R-1/q	R-0/q	R-q/q	R-0/q	R-0/q	R-q/q	R-0/0	R-0/q
T1OSCR	PLLR	OSTS	HFIOFR	HFIOFL	MFIOFR	LFIOFR	HFIOFS
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	q = Conditional

bit 7 **T1OSCR:** Timer1 Oscillator Ready bit
If T1OSCEN = 1:
1 = Timer1 oscillator is ready
0 = Timer1 oscillator is not ready
If T1OSCEN = 0:
1 = Timer1 clock source is always ready

bit 6 **PLLR** 4x PLL Ready bit
1 = 4x PLL is ready
0 = 4x PLL is not ready

bit 5 **OSTS:** Oscillator Start-up Time-out Status bit
1 = Running from the clock defined by the FOSC<2:0> bits of the Configuration Words
0 = Running from an internal oscillator (FOSC<2:0> = 100)

bit 4 **HFIOFR:** High Frequency Internal Oscillator Ready bit
1 = HFINTOSC is ready
0 = HFINTOSC is not ready

bit 3 **HFIOFL:** High Frequency Internal Oscillator Locked bit
1 = HFINTOSC is at least 2% accurate
0 = HFINTOSC is not 2% accurate

bit 2 **MFIOFR:** Medium Frequency Internal Oscillator Ready bit
1 = MFINTOSC is ready
0 = MFINTOSC is not ready

bit 1 **LFIOFR:** Low Frequency Internal Oscillator Ready bit
1 = LFINTOSC is ready
0 = LFINTOSC is not ready

bit 0 **HFIOFS:** High Frequency Internal Oscillator Stable bit
1 = HFINTOSC is at least 0.5% accurate
0 = HFINTOSC is not 0.5% accurate

REGISTER 8-4: PIE3: PERIPHERAL INTERRUPT ENABLE REGISTER 3

U-0	U-0	R/W-0/0	R/W-0/0	R/W-0/0	U-0	R/W-0/0	U-0
—	—	CCP4IE	CCP3IE	TMR6IE	—	TMR4IE	—
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-6 **Unimplemented:** Read as '0'

bit 5 **CCP4IE:** CCP4 Interrupt Enable bit
- 1 = Enables the CCP4 interrupt
- 0 = Disables the CCP4 interrupt

bit 4 **CCP3IE:** CCP3 Interrupt Enable bit
- 1 = Enables the CCP3 interrupt
- 0 = Disables the CCP3 interrupt

bit 3 **TMR6IE:** TMR6 to PR6 Match Interrupt Enable bit
- 1 = Enables the TMR6 to PR6 Match interrupt
- 0 = Disables the TMR6 to PR6 Match interrupt

bit 2 **Unimplemented:** Read as '0'

bit 1 **TMR4IE:** TMR4 to PR4 Match Interrupt Enable bit
- 1 = Enables the TMR4 to PR4 Match interrupt
- 0 = Disables the TMR4 to PR4 Match interrupt

bit 0 **Unimplemented:** Read as '0'

Note 1: Bit PEIE of the INTCON register must be set to enable any peripheral interrupt.

11.3.2 ERASING FLASH PROGRAM MEMORY

While executing code, program memory can only be erased by rows. To erase a row:

1. Load the EEADRH:EEADRL register pair with the address of new row to be erased.
2. Clear the CFGS bit of the EECON1 register.
3. Set the EEPGD, FREE and WREN bits of the EECON1 register.
4. Write 55h, then AAh, to EECON2 (Flash programming unlock sequence).
5. Set control bit WR of the EECON1 register to begin the erase operation.
6. Poll the FREE bit in the EECON1 register to determine when the row erase has completed.

See Example 11-4.

After the "`BSF EECON1,WR`" instruction, the processor requires two cycles to set up the erase operation. The user must place two `NOP` instructions after the WR bit is set. The processor will halt internal operations for the typical 2 ms erase time. This is not Sleep mode as the clocks and peripherals will continue to run. After the erase cycle, the processor will resume operation with the third instruction after the EECON1 write instruction.

11.3.3 WRITING TO FLASH PROGRAM MEMORY

Program memory is programmed using the following steps:

1. Load the starting address of the word(s) to be programmed.
2. Load the write latches with data.
3. Initiate a programming operation.
4. Repeat steps 1 through 3 until all data is written.

Before writing to program memory, the word(s) to be written must be erased or previously unwritten. Program memory can only be erased one row at a time. No automatic erase occurs upon the initiation of the write.

Program memory can be written one or more words at a time. The maximum number of words written at one time is equal to the number of write latches. See Figure 11-2 (block writes to program memory with 32 write latches) for more details. The write latches are aligned to the address boundary defined by EEADRL as shown in Table 11-1. Write operations do not cross these boundaries. At the completion of a program memory write operation, the write latches are reset to contain 0x3FFF.

The following steps should be completed to load the write latches and program a block of program memory. These steps are divided into two parts. First, all write latches are loaded with data except for the last program memory location. Then, the last write latch is loaded and the programming sequence is initiated. A special unlock sequence is required to load a write latch with data or initiate a Flash programming operation. This unlock sequence should not be interrupted.

1. Set the EEPGD and WREN bits of the EECON1 register.
2. Clear the CFGS bit of the EECON1 register.
3. Set the LWLO bit of the EECON1 register. When the LWLO bit of the EECON1 register is '`1`', the write sequence will only load the write latches and will not initiate the write to Flash program memory.
4. Load the EEADRH:EEADRL register pair with the address of the location to be written.
5. Load the EEDATH:EEDATL register pair with the program memory data to be written.
6. Write 55h, then AAh, to EECON2, then set the WR bit of the EECON1 register (Flash programming unlock sequence). The write latch is now loaded.
7. Increment the EEADRH:EEADRL register pair to point to the next location.
8. Repeat steps 5 through 7 until all but the last write latch has been loaded.
9. Clear the LWLO bit of the EECON1 register. When the LWLO bit of the EECON1 register is '`0`', the write sequence will initiate the write to Flash program memory.
10. Load the EEDATH:EEDATL register pair with the program memory data to be written.
11. Write 55h, then AAh, to EECON2, then set the WR bit of the EECON1 register (Flash programming unlock sequence). The entire latch block is now written to Flash program memory.

It is not necessary to load the entire write latch block with user program data. However, the entire write latch block will be written to program memory.

An example of the complete write sequence for eight words is shown in Example 11-5. The initial address is loaded into the EEADRH:EEADRL register pair; the eight words of data are loaded using indirect addressing.

Note:	If the number of write latches is smaller than the erase block size, the code sequence provided in Example 11-5 must be repeated multiple times to fully program an erased program memory row.

11.6 Write/Verify

Depending on the application, good programming practice may dictate that the value written to the data EEPROM or program memory should be verified (see Example 11-6) to the desired value to be written. Example 11-6 shows how to verify a write to EEPROM.

EXAMPLE 11-6: EEPROM WRITE/VERIFY

```
BANKSEL EEDATL      ;
MOVF    EEDATL, W   ;EEDATL not changed
                    ;from previous write
BSF     EECON1, RD  ;YES, Read the
                    ;value written
XORWF   EEDATL, W   ;
BTFSS   STATUS, Z   ;Is data the same
GOTO    WRITE_ERR   ;No, handle error
:                   ;Yes, continue
```

14.0 FIXED VOLTAGE REFERENCE (FVR)

The Fixed Voltage Reference (FVR) is a stable voltage reference, independent of V_{DD}, with a nominal output level (V_{FVR}) of 1.024V. The output of the FVR can be configured to supply a reference voltage to the following:

- ADC input channel
- Comparator positive input
- Comparator negative input

The FVR can be enabled by setting the FVREN bit of the FVRCON register.

14.1 Independent Gain Amplifier

The output of the FVR supplied to the peripherals, (listed above), is routed through a programmable gain amplifier. Each amplifier can be programmed for a gain of 1x, 2x or 4x, to produce the three possible voltage levels.

The ADFVR<1:0> bits of the FVRCON register are used to enable and configure the gain amplifier settings for the reference supplied to the ADC module. Reference **Section 16.0 "Analog-to-Digital Converter (ADC) Module"** for additional information.

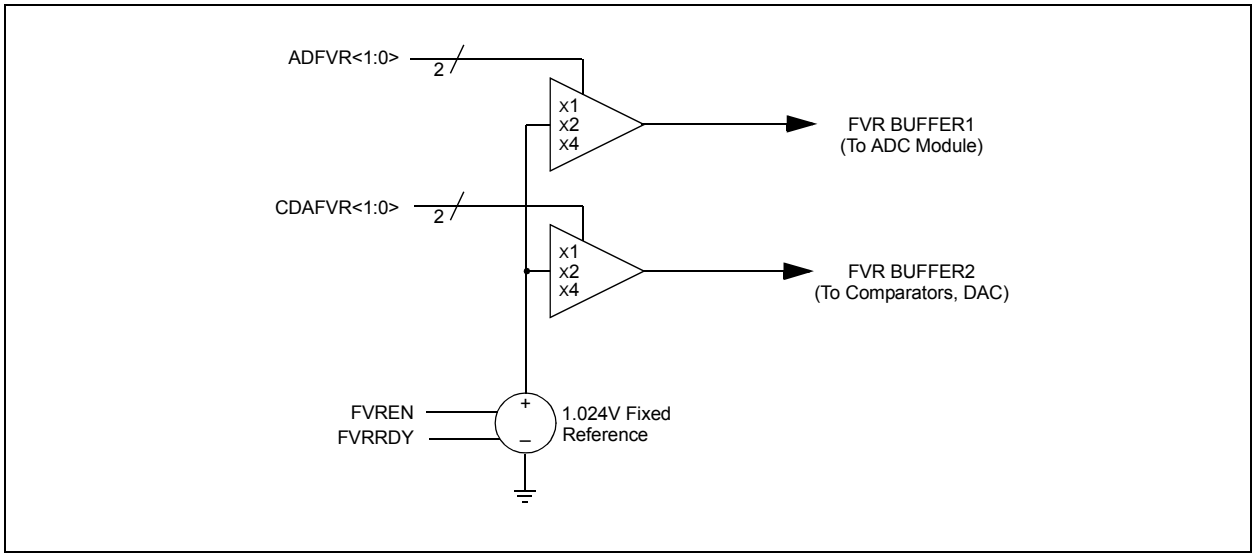
The CDAFVR<1:0> bits of the FVRCON register are used to enable and configure the gain amplifier settings for the reference supplied to the comparator modules. Reference **Section 19.0 "Comparator Module"** for additional information.

To minimize current consumption when the FVR is disabled, the FVR buffers should be turned off by clearing the Buffer Gain Selection bits.

14.2 FVR Stabilization Period

When the Fixed Voltage Reference module is enabled, it requires time for the reference and amplifier circuits to stabilize. Once the circuits stabilize and are ready for use, the FVRRDY bit of the FVRCON register will be set. See **Section 30.0 "Electrical Specifications"** for the minimum delay requirement.

FIGURE 14-1: VOLTAGE REFERENCE BLOCK DIAGRAM



14.3 Register Definitions: FVR Control

REGISTER 14-1: FVRCON: FIXED VOLTAGE REFERENCE CONTROL REGISTER

R/W-0/0	R-q/q	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
FVREN(1)	FVRRDY(2)	TSEN(3)	TSRNG(3)	CDAFVR<1:0>(1)		ADFVR<1:0>(1)	
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	q = Value depends on condition

bit 7 **FVREN:** Fixed Voltage Reference Enable bit(1)
1 = Fixed Voltage Reference is enabled
0 = Fixed Voltage Reference is disabled

bit 6 **FVRRDY:** Fixed Voltage Reference Ready Flag bit(2)
1 = Fixed Voltage Reference output is ready for use
0 = Fixed Voltage Reference output is not ready or not enabled

bit 5 **TSEN:** Temperature Indicator Enable bit(3)
1 = Temperature Indicator is enabled
0 = Temperature Indicator is disabled

bit 4 **TSRNG:** Temperature Indicator Range Selection bit(3)
1 = $V_{OUT} = V_{DD} - 4V_T$ (High Range)
0 = $V_{OUT} = V_{DD} - 2V_T$ (Low Range)

bit 3-2 **CDAFVR<1:0>:** Comparator FVR Buffer Gain Selection bits(1)
11 = Comparator FVR Buffer Gain is 4x, with output $V_{CDAFVR} = 4x\ V_{FVR}$(4)
10 = Comparator FVR Buffer Gain is 2x, with output $V_{CDAFVR} = 2x\ V_{FVR}$(4)
01 = Comparator FVR Buffer Gain is 1x, with output $V_{CDAFVR} = 1x\ V_{FVR}$
00 = Comparator FVR Buffer is off

bit 1-0 **ADFVR<1:0>:** ADC FVR Buffer Gain Selection bit(1)
11 = ADC FVR Buffer Gain is 4x, with output $V_{ADFVR} = 4x\ V_{FVR}$(4)
10 = ADC FVR Buffer Gain is 2x, with output $V_{ADFVR} = 2x\ V_{FVR}$(4)
01 = ADC FVR Buffer Gain is 1x, with output $V_{ADFVR} = 1x\ V_{FVR}$
00 = ADC FVR Buffer is off

Note 1: To minimize current consumption when the FVR is disabled, the FVR buffers should be turned off by clearing the Buffer Gain Selection bits.
2: FVRRDY is always '1' for the PIC16F1847 devices.
3: See **Section 15.0 "Temperature Indicator Module"** for additional information.
4: Fixed Voltage Reference output cannot exceed V_{DD}.

TABLE 14-1: SUMMARY OF REGISTERS ASSOCIATED WITH THE FIXED VOLTAGE REFERENCE

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on page
FVRCON	FVREN	FVRRDY	TSEN	TSRNG	CDAFVR>1:0>		ADFVR<1:0>		134

Legend: Shaded cells are unused by the Fixed Voltage Reference module.

15.0 TEMPERATURE INDICATOR MODULE

This family of devices is equipped with a temperature circuit designed to measure the operating temperature of the silicon die. The circuit's range of operating temperature falls between of -40°C and +85°C. The output is a voltage that is proportional to the device temperature. The output of the temperature indicator is internally connected to the device ADC.

The circuit may be used as a temperature threshold detector or a more accurate temperature indicator, depending on the level of calibration performed. A one-point calibration allows the circuit to indicate a temperature closely surrounding that point. A two-point calibration allows the circuit to sense the entire range of temperature more accurately. Reference Application Note AN1333, "*Use and Calibration of the Internal Temperature Indicator*" (DS01333) for more details regarding the calibration process.

15.1 Circuit Operation

Figure 15-1 shows a simplified block diagram of the temperature circuit. The proportional voltage output is achieved by measuring the forward voltage drop across multiple silicon junctions.

Equation 15-1 describes the output characteristics of the temperature indicator.

EQUATION 15-1: VOUT RANGES

High Range: $V_{OUT} = V_{DD} - 4V_T$

Low Range: $V_{OUT} = V_{DD} - 2V_T$

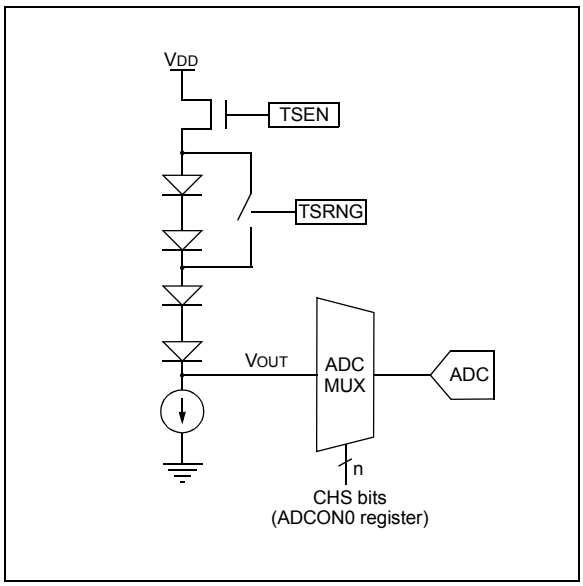
The temperature sense circuit is integrated with the Fixed Voltage Reference (FVR) module. See **Section TABLE 14-1: "Summary of Registers Associated with the Fixed Voltage Reference"** for more information.

The circuit is enabled by setting the TSEN bit of the FVRCON register (Register 14-1). When disabled, the circuit draws no current.

The circuit operates in either high or low range. The high range, selected by setting the TSRNG bit of the FVRCON register, provides a wider output voltage. This provides more resolution over the temperature range, but may be less consistent from part to part. This range requires a higher bias voltage to operate and thus, a higher VDD is needed.

The low range is selected by clearing the TSRNG bit of the FVRCON register. The low range generates a lower voltage drop and thus, a lower bias voltage is needed to operate the circuit. The low range is provided for low voltage operation.

FIGURE 15-1: TEMPERATURE CIRCUIT DIAGRAM



15.2 Minimum Operating VDD vs. Minimum Sensing Temperature

When the temperature circuit is operated in low range, the device may be operated at any operating voltage that is within specifications.

When the temperature circuit is operated in high range, the device operating voltage, VDD, must be high enough to ensure that the temperature circuit is correctly biased.

Table 15-1 shows the recommended minimum VDD vs. range setting.

TABLE 15-1: RECOMMENDED VDD VS. RANGE

Min. VDD, TSRNG = 1	Min. VDD, TSRNG = 0
3.6V	1.8V

15.3 Temperature Output

The output of the circuit is measured using the internal Analog-to-Digital Converter. A channel is reserved for the temperature circuit output. Refer to **Section 16.0 "Analog-to-Digital Converter (ADC) Module"** for detailed information.

15.4 ADC Acquisition Time

To ensure accurate temperature measurements, the user must wait at least 200 µs after the ADC input multiplexer is connected to the temperature indicator output before the conversion is performed. In addition, the user must wait 200 µs between sequential conversions of the temperature indicator output.

16.3 ADC Acquisition Requirements

For the ADC to meet its specified accuracy, the charge holding capacitor (CHOLD) must be allowed to fully charge to the input channel voltage level. The Analog Input model is shown in Figure 16-4. The source impedance (RS) and the internal sampling switch (RSS) impedance directly affect the time required to charge the capacitor CHOLD. The sampling switch (RSS) impedance varies over the device voltage (VDD), refer to Figure 16-4. **The maximum recommended impedance for analog sources is 10 kΩ.** As the source impedance is decreased, the acquisition time may be decreased. After the analog input channel is selected (or changed), an ADC acquisition must be done before the conversion can be started. To calculate the minimum acquisition time, Equation 16-1 may be used. This equation assumes that 1/2 LSb error is used (1,024 steps for the ADC). The 1/2 LSb error is the maximum error allowed for the ADC to meet its specified resolution.

EQUATION 16-1: ACQUISITION TIME EXAMPLE

Assumptions: $Temperature = 50°C$ *and external impedance of* $10k\Omega$ $5.0V$ V_{DD}

$$T_{ACQ} = \text{Amplifier Settling Time} + \text{Hold Capacitor Charging Time} + \text{Temperature Coefficient}$$
$$= T_{AMP} + T_C + T_{COFF}$$
$$= 2\mu s + T_C + [(\text{Temperature} - 25°C)(0.05\mu s/°C)]$$

The value for T_C *can be approximated with the following equations:*

$$V_{APPLIED}\left(1 - \frac{1}{(2^{n+1}) - 1}\right) = V_{CHOLD} \quad ;[1]\ V_{CHOLD}\ \text{charged to within 1/2 lsb}$$

$$V_{APPLIED}\left(1 - e^{\frac{-T_C}{RC}}\right) = V_{CHOLD} \quad ;[2]\ V_{CHOLD}\ \text{charge response to}\ V_{APPLIED}$$

$$V_{APPLIED}\left(1 - e^{\frac{-T_C}{RC}}\right) = V_{APPLIED}\left(1 - \frac{1}{(2^{n+1}) - 1}\right) \quad ;\text{combining [1] and [2]}$$

Note: Where n = number of bits of the ADC.

Solving for T_C*:*

$$T_C = -C_{HOLD}(R_{IC} + R_{SS} + R_S)\ ln(1/2047)$$
$$= -10pF(1k\Omega + 7k\Omega + 10k\Omega)\ ln(0.0004885)$$
$$= 1.37\mu s$$

Therefore:

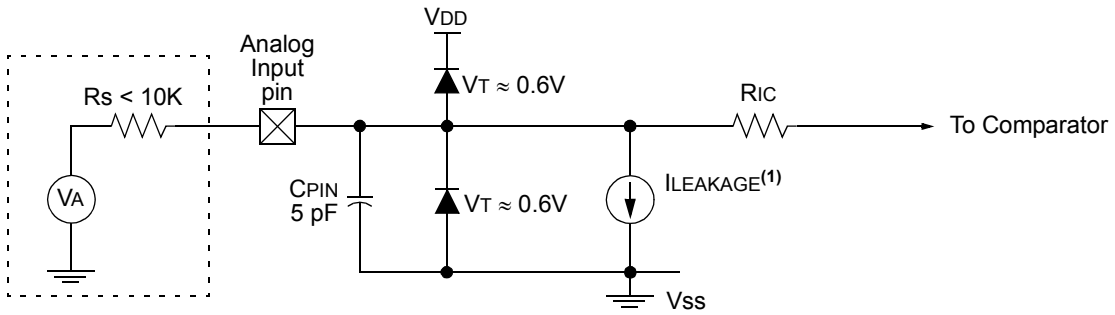
$$T_{ACQ} = 2\mu s + 1.37\mu s + [(50°C - 25°C)(0.05\mu s/°C)]$$
$$= 4.62\mu s$$

Note 1: The reference voltage (VREF) has no effect on the equation, since it cancels itself out.

2: The charge holding capacitor (CHOLD) is not discharged after each conversion.

3: The maximum recommended impedance for analog sources is 10 kΩ. This is required to meet the pin leakage specification.

FIGURE 19-4: ANALOG INPUT MODEL



Legend: CPIN = Input Capacitance
ILEAKAGE = Leakage Current at the pin due to various junctions
RIC = Interconnect Resistance
RS = Source Impedance
VA = Analog Voltage
VT = Threshold Voltage

Note 1: See **Section 30.0 "Electrical Specifications"**.

TABLE 19-2: SUMMARY OF REGISTERS ASSOCIATED WITH COMPARATOR MODULE

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
ANSELA	—	—	—	ANSA4	ANSA3	ANSA2	ANSA1	ANSA0	122
CM1CON0	C1ON	C1OUT	C1OE	C1POL	—	C1SP	C1HYS	C1SYNC	170
CM1CON1	C1NTP	C1INTN	C1PCH<1:0>		—	—	C1NCH<1:0>		171
CM2CON0	C2ON	C2OUT	C2OE	C2POL	—	C2SP	C2HYS	C2SYNC	171
CM2CON1	C2NTP	C2INTN	C2PCH<1:0>		—	—	C2NCH<1:0>		171
CMOUT	—	—	—	—	—	—	MC2OUT	MC1OUT	171
DACCON0	DACEN	DACLPS	DACOE	—	DACPSS<1:0>		—	DACNSS	154
DACCON1	—	—	—	DACR<4:0>					154
FVRCON	FVREN	FVRRDY	TSEN	TSRNG	CDAFVR<1:0>		ADFVR<1:0>		134
INTCON	GIE	PEIE	TMR0IE	INTE	IOCE	TMR0IF	INTF	IOCF	88
LATA	LATA7	LATA6	—	LATA4	LATA3	LATA2	LATA1	LATA0	121
PIE2	OSFIE	C2IE	C1IE	EEIE	BCL1IE	—	—	CCP2IE	90
PIR2	OSFIF	C2IF	C1IF	EEIF	BCL1IF	—	—	CCP2IF	94
PORTA	RA7	RA6	RA5	RA4	RA3	RA2	RA1	RA0	120
TRISA	TRISA7	TRISA6	TRISA5	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	120

Legend: — = unimplemented, read as '0'. Shaded cells are unused by the comparator module.

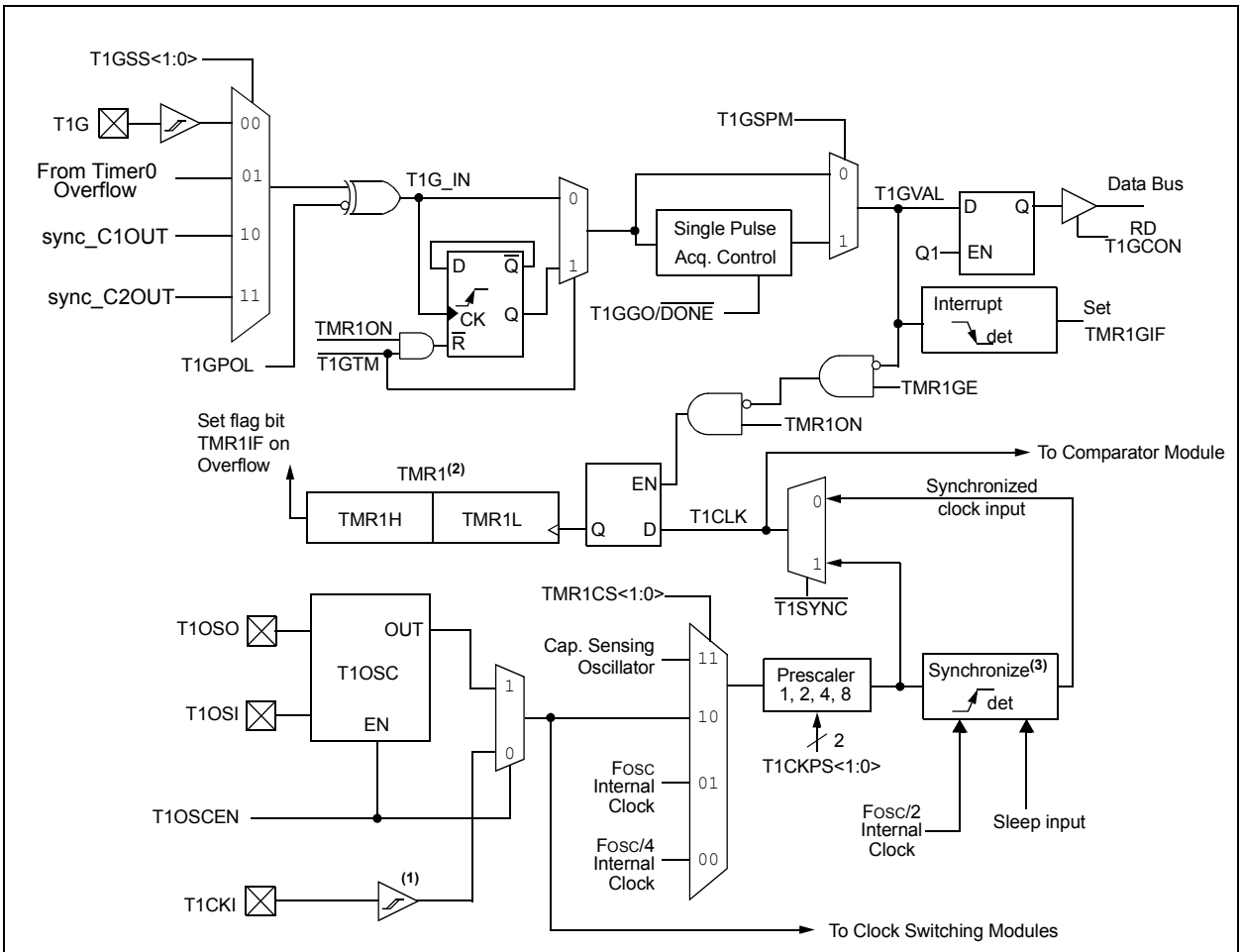
21.0 TIMER1 MODULE WITH GATE CONTROL

The Timer1 module is a 16-bit timer/counter with the following features:

- 16-bit timer/counter register pair (TMR1H:TMR1L)
- Programmable internal or external clock source
- 2-bit prescaler
- Dedicated 32 kHz oscillator circuit
- Optionally synchronized comparator out
- Multiple Timer1 gate (count enable) sources
- Interrupt on overflow
- Wake-up on overflow (external clock, Asynchronous mode only)
- Time base for the Capture/Compare function
- Special Event Trigger (with CCP/ECCP)
- Selectable Gate Source Polarity
- Gate Toggle Mode
- Gate Single-pulse Mode
- Gate Value Status
- Gate Event Interrupt

Figure 21-1 is a block diagram of the Timer1 module.

FIGURE 21-1: TIMER1 BLOCK DIAGRAM



Note 1: ST Buffer is high speed type when using T1CKI.
2: Timer1 register increments on rising edge.
3: Synchronize does not operate while in Sleep.

FIGURE 23-4: CARRIER LOW SYNCHRONIZATION (MDSHSYNC = 0, MDCLSYNC = 1)

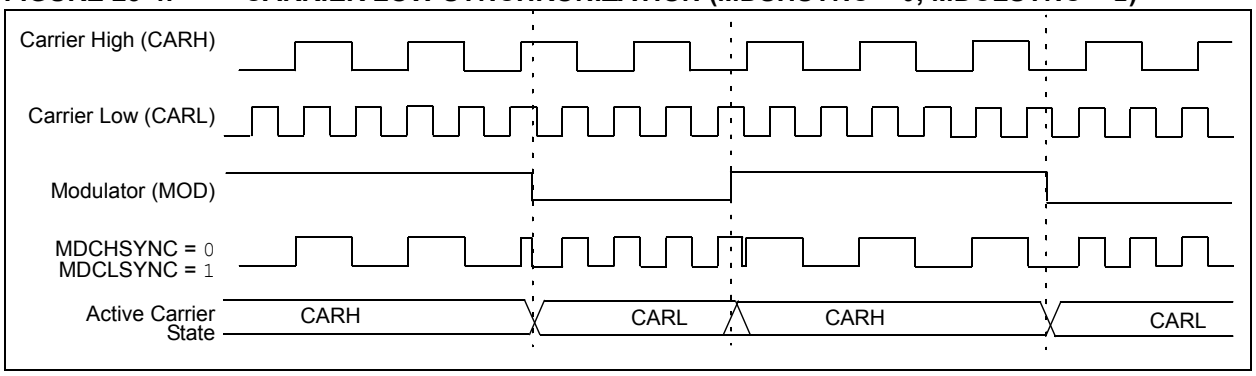
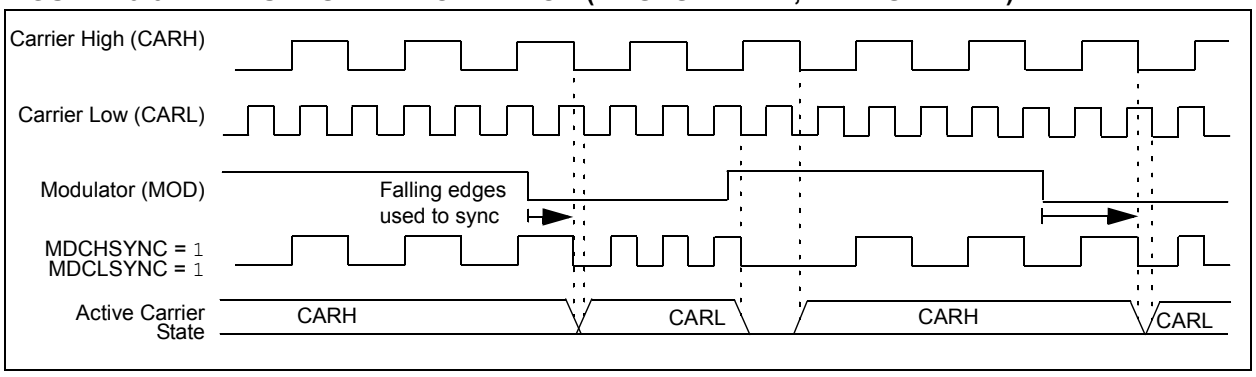


FIGURE 23-5: FULL SYNCHRONIZATION (MDSHSYNC = 1, MDCLSYNC = 1)



24.4.2 FULL-BRIDGE MODE

In Full-Bridge mode, all four pins are used as outputs. An example of Full-Bridge application is shown in Figure 24-10.

In the Forward mode, pin CCPx/PxA is driven to its active state, pin PxD is modulated, while PxB and PxC will be driven to their inactive state as shown in Figure 24-11.

In the Reverse mode, PxC is driven to its active state, pin PxB is modulated, while PxA and PxD will be driven to their inactive state as shown Figure 24-12.

PxA, PxB, PxC and PxD outputs are multiplexed with the PORT data latches. The associated TRIS bits must be cleared to configure the PxA, PxB, PxC and PxD pins as outputs.

FIGURE 24-10: EXAMPLE OF FULL-BRIDGE APPLICATION

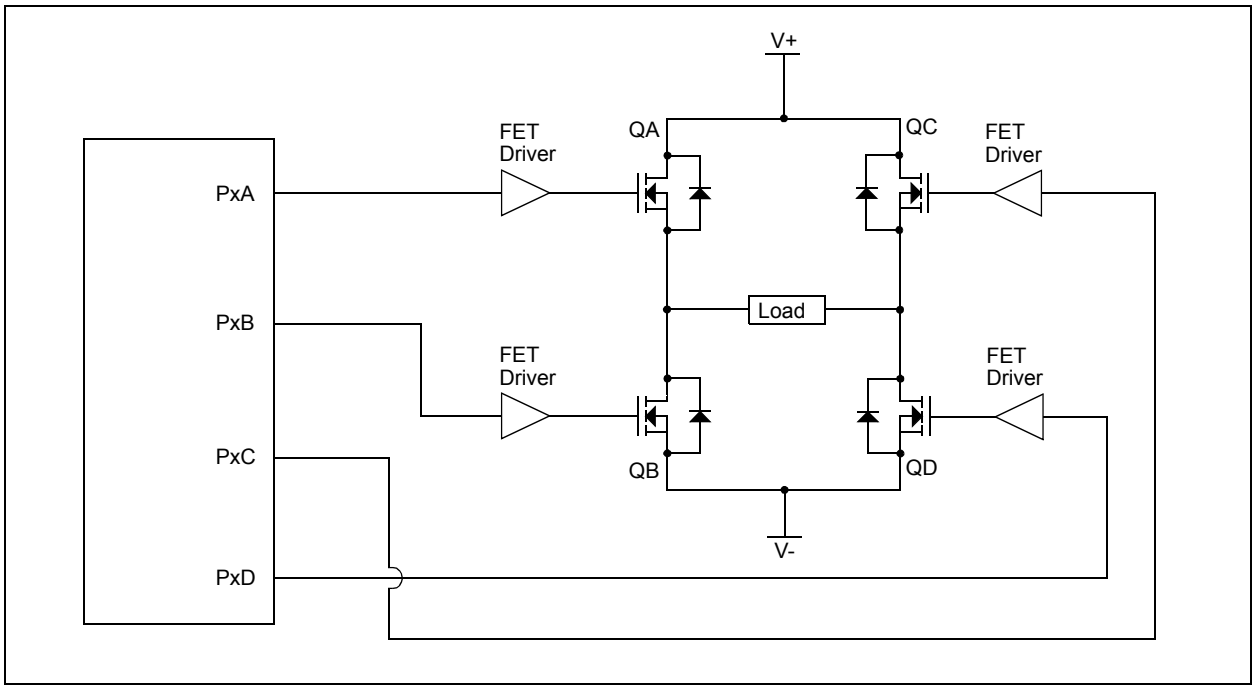
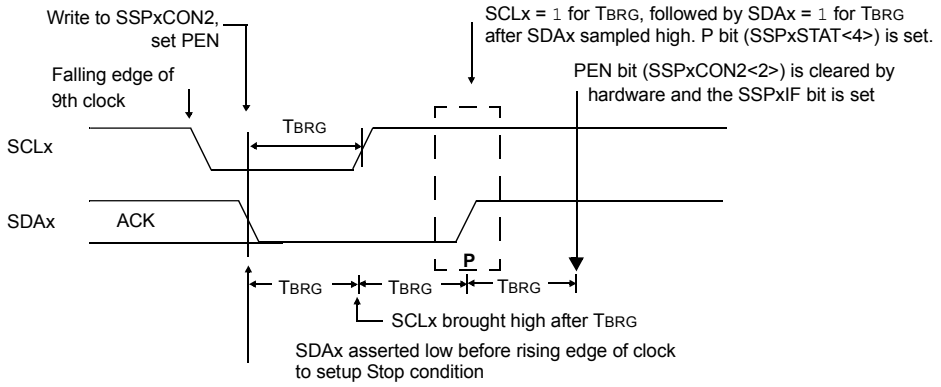


FIGURE 25-31: STOP CONDITION RECEIVE OR TRANSMIT MODE



Note: TBRG = one Baud Rate Generator period.

25.6.10 SLEEP OPERATION

While in Sleep mode, the I^{2}C Slave module can receive addresses or data and when an address match or complete byte transfer occurs, wake the processor from Sleep (if the MSSPx interrupt is enabled).

25.6.11 EFFECTS OF A RESET

A Reset disables the MSSPx module and terminates the current transfer.

25.6.12 MULTI-MASTER MODE

In Multi-Master mode, the interrupt generation on the detection of the Start and Stop conditions allows the determination of when the bus is free. The Stop (P) and Start (S) bits are cleared from a Reset or when the MSSPx module is disabled. Control of the I^{2}C bus may be taken when the P bit of the SSPxSTAT register is set, or the bus is Idle, with both the S and P bits clear. When the bus is busy, enabling the SSPx interrupt will generate the interrupt when the Stop condition occurs.

In multi-master operation, the SDAx line must be monitored for arbitration to see if the signal level is the expected output level. This check is performed by hardware with the result placed in the BCLxIF bit.

The states where arbitration can be lost are:

- Address Transfer
- Data Transfer
- A Start Condition
- A Repeated Start Condition
- An Acknowledge Condition

25.6.13 MULTI -MASTER COMMUNICATION, BUS COLLISION AND BUS ARBITRATION

Multi-Master mode support is achieved by bus arbitration. When the master outputs address/data bits onto the SDAx pin, arbitration takes place when the master outputs a '1' on SDAx, by letting SDAx float high and another master asserts a '0'. When the SCLx pin floats high, data should be stable. If the expected data on SDAx is a '1' and the data sampled on the SDAx pin is '0', then a bus collision has taken place. The master will set the Bus Collision Interrupt Flag, BCLxIF and reset the I^{2}C port to its Idle state (Figure 25-32).

If a transmit was in progress when the bus collision occurred, the transmission is halted, the BF flag is cleared, the SDAx and SCLx lines are deasserted and the SSPxBUF can be written to. When the user services the bus collision Interrupt Service Routine and if the I^{2}C bus is free, the user can resume communication by asserting a Start condition.

If a Start, Repeated Start, Stop or Acknowledge condition was in progress when the bus collision occurred, the condition is aborted, the SDAx and SCLx lines are deasserted and the respective control bits in the SSPxCON2 register are cleared. When the user services the bus collision Interrupt Service Routine and if the I^{2}C bus is free, the user can resume communication by asserting a Start condition.

The master will continue to monitor the SDAx and SCLx pins. If a Stop condition occurs, the SSPxIF bit will be set.

A write to the SSPxBUF will start the transmission of data at the first data bit, regardless of where the transmitter left off when the bus collision occurred.

In Multi-Master mode, the interrupt generation on the detection of Start and Stop conditions allows the determination of when the bus is free. Control of the I^{2}C bus can be taken when the P bit is set in the SSPxSTAT register, or the bus is Idle and the S and P bits are cleared.

REGISTER 25-3: SSPxCON2: SSPx CONTROL REGISTER 2

R/W-0/0	R-0/0	R/W-0/0	R/S/HS-0/0	R/S/HS-0/0	R/S/HS-0/0	R/S/HS-0/0	R/W/HS-0/0
GCEN	ACKSTAT	ACKDT	ACKEN	RCEN	PEN	RSEN	SEN
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	HC = Cleared by hardware S = User set

bit 7 **GCEN:** General Call Enable bit (in I^2C Slave mode only)
1 = Enable interrupt when a general call address (0x00 or 00h) is received in the SSPxSR
0 = General call address disabled

bit 6 **ACKSTAT:** Acknowledge Status bit (in I^2C mode only)
1 = Acknowledge was not received
0 = Acknowledge was received

bit 5 **ACKDT:** Acknowledge Data bit (in I^2C mode only)
In Receive mode:
Value transmitted when the user initiates an Acknowledge sequence at the end of a receive
1 = Not Acknowledge
0 = Acknowledge

bit 4 **ACKEN:** Acknowledge Sequence Enable bit (in I^2C Master mode only)
In Master Receive mode:
1 = Initiate Acknowledge sequence on SDAx and SCLx pins, and transmit ACKDT data bit. Automatically cleared by hardware.
0 = Acknowledge sequence idle

bit 3 **RCEN:** Receive Enable bit (in I^2C Master mode only)
1 = Enables Receive mode for I^2C
0 = Receive idle

bit 2 **PEN:** Stop Condition Enable bit (in I^2C Master mode only)
SCKx Release Control:
1 = Initiate Stop condition on SDAx and SCLx pins. Automatically cleared by hardware.
0 = Stop condition Idle

bit 1 **RSEN:** Repeated Start Condition Enable bit (in I^2C Master mode only)
1 = Initiate Repeated Start condition on SDAx and SCLx pins. Automatically cleared by hardware.
0 = Repeated Start condition Idle

bit 0 **SEN:** Start Condition Enable/Stretch Enable bit
In Master mode:
1 = Initiate Start condition on SDAx and SCLx pins. Automatically cleared by hardware.
0 = Start condition Idle
In Slave mode:
1 = Clock stretching is enabled for both slave transmit and slave receive (stretch enabled)
0 = Clock stretching is disabled

Note 1: For bits ACKEN, RCEN, PEN, RSEN, SEN: If the I^2C module is not in the Idle mode, this bit may not be set (no spooling) and the SSPxBUF may not be written (or writes to the SSPxBUF are disabled).

26.1.2.8 Asynchronous Reception Setup:

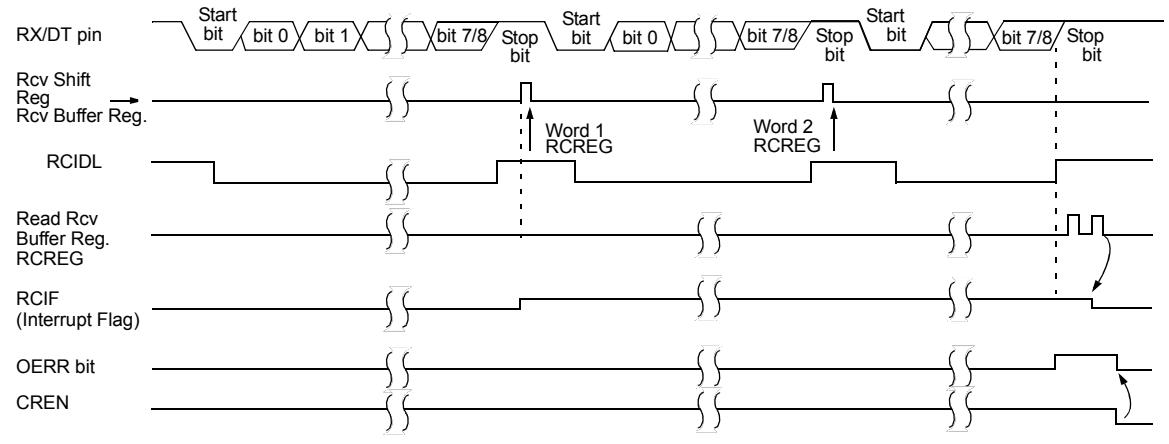
1. Initialize the SPBRGH, SPBRGL register pair and the BRGH and BRG16 bits to achieve the desired baud rate (see **Section 26.3 "EUSART Baud Rate Generator (BRG)"**).
2. Clear the ANSEL bit for the RX pin (if applicable).
3. Enable the serial port by setting the SPEN bit. The SYNC bit must be clear for asynchronous operation.
4. If interrupts are desired, set the RCIE bit of the PIE1 register and the GIE and PEIE bits of the INTCON register.
5. If 9-bit reception is desired, set the RX9 bit.
6. Enable reception by setting the CREN bit.
7. The RCIF interrupt flag bit will be set when a character is transferred from the RSR to the receive buffer. An interrupt will be generated if the RCIE interrupt enable bit was also set.
8. Read the RCSTA register to get the error flags and, if 9-bit data reception is enabled, the 9th data bit.
9. Get the received eight Least Significant data bits from the receive buffer by reading the RCREG register.
10. If an overrun occurred, clear the OERR flag by clearing the CREN receiver enable bit.

26.1.2.9 9-bit Address Detection Mode Setup

This mode would typically be used in RS-485 systems. To set up an Asynchronous Reception with Address Detect Enable:

1. Initialize the SPBRGH, SPBRGL register pair and the BRGH and BRG16 bits to achieve the desired baud rate (see **Section 26.3 "EUSART Baud Rate Generator (BRG)"**).
2. Clear the ANSEL bit for the RX pin (if applicable).
3. Enable the serial port by setting the SPEN bit. The SYNC bit must be clear for asynchronous operation.
4. If interrupts are desired, set the RCIE bit of the PIE1 register and the GIE and PEIE bits of the INTCON register.
5. Enable 9-bit reception by setting the RX9 bit.
6. Enable address detection by setting the ADDEN bit.
7. Enable reception by setting the CREN bit.
8. The RCIF interrupt flag bit will be set when a character with the 9th bit set is transferred from the RSR to the receive buffer. An interrupt will be generated if the RCIE interrupt enable bit was also set.
9. Read the RCSTA register to get the error flags. The 9th data bit will always be set.
10. Get the received eight Least Significant data bits from the receive buffer by reading the RCREG register. Software determines if this is the device's address.
11. If an overrun occurred, clear the OERR flag by clearing the CREN receiver enable bit.
12. If the device has been addressed, clear the ADDEN bit to allow all received data into the receive buffer and generate interrupts.

FIGURE 26-5: ASYNCHRONOUS RECEPTION



Note: This timing diagram shows three words appearing on the RX input. The RCREG (receive buffer) is read after the third word, causing the OERR (overrun) bit to be set.

TABLE 26-5: BAUD RATES FOR ASYNCHRONOUS MODES (CONTINUED)

BAUD RATE	SYNC = 0, BRGH = 1, BRG16 = 0											
	Fosc = 8.000 MHz			Fosc = 4.000 MHz			Fosc = 3.6864 MHz			Fosc = 1.000 MHz		
	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)
300	—	—	—	—	—	—	—	—	—	300	0.16	207
1200	—	—	—	1202	0.16	207	1200	0.00	191	1202	0.16	51
2400	2404	0.16	207	2404	0.16	103	2400	0.00	95	2404	0.16	25
9600	9615	0.16	51	9615	0.16	25	9600	0.00	23	—	—	—
10417	10417	0.00	47	10417	0.00	23	10473	0.53	21	10417	0.00	5
19.2k	19231	0.16	25	19.23k	0.16	12	19.2k	0.00	11	—	—	—
57.6k	55556	-3.55	8	—	—	—	57.60k	0.00	3	—	—	—
115.2k	—	—	—	—	—	—	115.2k	0.00	1	—	—	—

BAUD RATE	SYNC = 0, BRGH = 0, BRG16 = 1											
	Fosc = 32.000 MHz			Fosc = 20.000 MHz			Fosc = 18.432 MHz			Fosc = 11.0592 MHz		
	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)
300	300.0	0.00	6666	300.0	-0.01	4166	300.0	0.00	3839	300.0	0.00	2303
1200	1200	-0.02	3332	1200	-0.03	1041	1200	0.00	959	1200	0.00	575
2400	2401	-0.04	832	2399	-0.03	520	2400	0.00	479	2400	0.00	287
9600	9615	0.16	207	9615	0.16	129	9600	0.00	119	9600	0.00	71
10417	10417	0.00	191	10417	0.00	119	10378	-0.37	110	10473	0.53	65
19.2k	19.23k	0.16	103	19.23k	0.16	64	19.20k	0.00	59	19.20k	0.00	35
57.6k	57.14k	-0.79	34	56.818	-1.36	21	57.60k	0.00	19	57.60k	0.00	11
115.2k	117.6k	2.12	16	113.636	-1.36	10	115.2k	0.00	9	115.2k	0.00	5

BAUD RATE	SYNC = 0, BRGH = 0, BRG16 = 1											
	Fosc = 8.000 MHz			Fosc = 4.000 MHz			Fosc = 3.6864 MHz			Fosc = 1.000 MHz		
	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)
300	299.9	-0.02	1666	300.1	0.04	832	300.0	0.00	767	300.5	0.16	207
1200	1199	-0.08	416	1202	0.16	207	1200	0.00	191	1202	0.16	51
2400	2404	0.16	207	2404	0.16	103	2400	0.00	95	2404	0.16	25
9600	9615	0.16	51	9615	0.16	25	9600	0.00	23	—	—	—
10417	10417	0.00	47	10417	0.00	23	10473	0.53	21	10417	0.00	5
19.2k	19.23k	0.16	25	19.23k	0.16	12	19.20k	0.00	11	—	—	—
57.6k	55556	-3.55	8	—	—	—	57.60k	0.00	3	—	—	—
115.2k	—	—	—	—	—	—	115.2k	0.00	1	—	—	—

TABLE 26-7: SUMMARY OF REGISTERS ASSOCIATED WITH SYNCHRONOUS MASTER TRANSMISSION

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
APFCON0	RXDTSEL	SDO1SEL	SS1SEL	P2BSEL	CCP2SEL	P1DSEL	P1CSEL	CCP1SEL	118
APFCON1	—	—	—	—	—	—	—	TXCKSEL	118
BAUDCON	ABDOVF	RCIDL	—	SCKP	BRG16	—	WUE	ABDEN	298
INTCON	GIE	PEIE	TMR0IE	INTE	IOCE	TMR0IF	INTF	IOCF	88
PIE1	TMR1GIE	ADIE	RCIE	TXIE	SSP1IE	CCP1IE	TMR2IE	TMR1IE	89
PIR1	TMR1GIF	ADIF	RCIF	TXIF	SSP1IF	CCP1IF	TMR2IF	TMR1IF	93
RCSTA	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D	297
SPBRGL	BRG<7:0>								299*
SPBRGH	BRG<15:8>								299*
TRISB	TRISB7	TRISB6	TRISB5	TRISB4	TRISB3	TRISB2	TRISB1	TRISB0	126
TXREG	EUSART Transmit Data Register								289*
TXSTA	CSRC	TX9	TXEN	SYNC	SENDB	BRGH	TRMT	TX9D	296

Legend: — = unimplemented location, read as '0'. Shaded cells are not used for Synchronous Master Transmission.

* Page provides register information.

TABLE 30-16: COMPARATOR SPECIFICATIONS(1)

Operating Conditions (unless otherwise stated) VDD = 3.0V, TA = 25°C							
Param. No.	**Sym.**	**Characteristics**	**Min.**	**Typ.**	**Max.**	**Units**	**Comments**
CM01	VIOFF	Input Offset Voltage	—	±7.5	±60	mV	CxSP = 1 VICM = VDD/2
CM02	VICM	Input Common Mode Voltage	0	—	VDD	V	
CM03	CMRR	Common Mode Rejection Ratio	—	50	—	dB	
CM04A	TRESP(2)	Response Time Rising Edge	—	400	800	ns	CxSP = 1
CM04B		Response Time Falling Edge	—	200	400	ns	CxSP = 1
CM04C		Response Time Rising Edge	—	1200	—	ns	CxSP = 0
CM04D		Response Time Falling Edge	—	550	—	ns	CxSP = 0
CM05	TMC2OV	Comparator Mode Change to Output Valid*	—	—	10	µs	
CM06	CHYSTER	Comparator Hysteresis	— —	50 10	— —	mV mV	CxHYS = 1, CxSP = 1 CxHYS = 1, CxSP = 0

* These parameters are characterized but not tested.

Note 1: See **Section 31.0 "DC and AC Characteristics Graphs and Charts"** for operating characterization.

2: Response time measured with one comparator input at VDD/2, while the other input transitions from VSS to VDD.

TABLE 30-17: DIGITAL-TO-ANALOG CONVERTER (DAC) SPECIFICATIONS(1)

Operating Conditions (unless otherwise stated) VDD = 3.0V, TA = 25°C							
Param. No.	**Sym.**	**Characteristics**	**Min.**	**Typ.**	**Max.**	**Units**	**Comments**
DAC01*	CLSB	Step Size	—	VDD/32	—	V	
DAC02*	CACC	Absolute Accuracy	—	—	± 1/2	LSb	
DAC03*	CR	Unit Resistor Value (R)	—	5000	—	Ω	
DAC04*	CST	Settling Time(2)	—	—	10	µs	

* These parameters are characterized but not tested.

Note 1: See **Section 31.0 "DC and AC Characteristics Graphs and Charts"** for operating characterization.

2: Settling time measured while DACR<4:0> transitions from '0000' to '1111'.

32.7 MPLAB SIM Software Simulator

The MPLAB SIM Software Simulator allows code development in a PC-hosted environment by simulating the PIC MCUs and dsPIC® DSCs on an instruction level. On any given instruction, the data areas can be examined or modified and stimuli can be applied from a comprehensive stimulus controller. Registers can be logged to files for further run-time analysis. The trace buffer and logic analyzer display extend the power of the simulator to record and track program execution, actions on I/O, most peripherals and internal registers.

The MPLAB SIM Software Simulator fully supports symbolic debugging using the MPLAB C Compilers, and the MPASM and MPLAB Assemblers. The software simulator offers the flexibility to develop and debug code outside of the hardware laboratory environment, making it an excellent, economical software development tool.

32.8 MPLAB REAL ICE In-Circuit Emulator System

MPLAB REAL ICE In-Circuit Emulator System is Microchip's next generation high-speed emulator for Microchip Flash DSC and MCU devices. It debugs and programs PIC® Flash MCUs and dsPIC® Flash DSCs with the easy-to-use, powerful graphical user interface of the MPLAB Integrated Development Environment (IDE), included with each kit.

The emulator is connected to the design engineer's PC using a high-speed USB 2.0 interface and is connected to the target with either a connector compatible with in-circuit debugger systems (RJ11) or with the new high-speed, noise tolerant, Low-Voltage Differential Signal (LVDS) interconnection (CAT5).

The emulator is field upgradable through future firmware downloads in MPLAB IDE. In upcoming releases of MPLAB IDE, new devices will be supported, and new features will be added. MPLAB REAL ICE offers significant advantages over competitive emulators including low-cost, full-speed emulation, run-time variable watches, trace analysis, complex breakpoints, a ruggedized probe interface and long (up to three meters) interconnection cables.

32.9 MPLAB ICD 3 In-Circuit Debugger System

MPLAB ICD 3 In-Circuit Debugger System is Microchip's most cost effective high-speed hardware debugger/programmer for Microchip Flash Digital Signal Controller (DSC) and microcontroller (MCU) devices. It debugs and programs PIC® Flash microcontrollers and dsPIC® DSCs with the powerful, yet easy-to-use graphical user interface of MPLAB Integrated Development Environment (IDE).

The MPLAB ICD 3 In-Circuit Debugger probe is connected to the design engineer's PC using a high-speed USB 2.0 interface and is connected to the target with a connector compatible with the MPLAB ICD 2 or MPLAB REAL ICE systems (RJ-11). MPLAB ICD 3 supports all MPLAB ICD 2 headers.

32.10 PICkit 3 In-Circuit Debugger/ Programmer and PICkit 3 Debug Express

The MPLAB PICkit 3 allows debugging and programming of PIC® and dsPIC® Flash microcontrollers at a most affordable price point using the powerful graphical user interface of the MPLAB Integrated Development Environment (IDE). The MPLAB PICkit 3 is connected to the design engineer's PC using a full speed USB interface and can be connected to the target via an Microchip debug (RJ-11) connector (compatible with MPLAB ICD 3 and MPLAB REAL ICE). The connector uses two device I/O pins and the reset line to implement in-circuit debugging and In-Circuit Serial Programming™.

The PICkit 3 Debug Express include the PICkit 3, demo board and microcontroller, hookup cables and CDROM with user's guide, lessons, tutorial, compiler and MPLAB IDE software.